

Page 2 **BLOCK DIAGRAM**

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Page 4 **ANALOG FRONT END PGA +REF+TEMP SENSOR**

Page 5 **ISOLATED RS485 INTERFACE**

Page 6 **LAUNCH PAD INTERFACE**

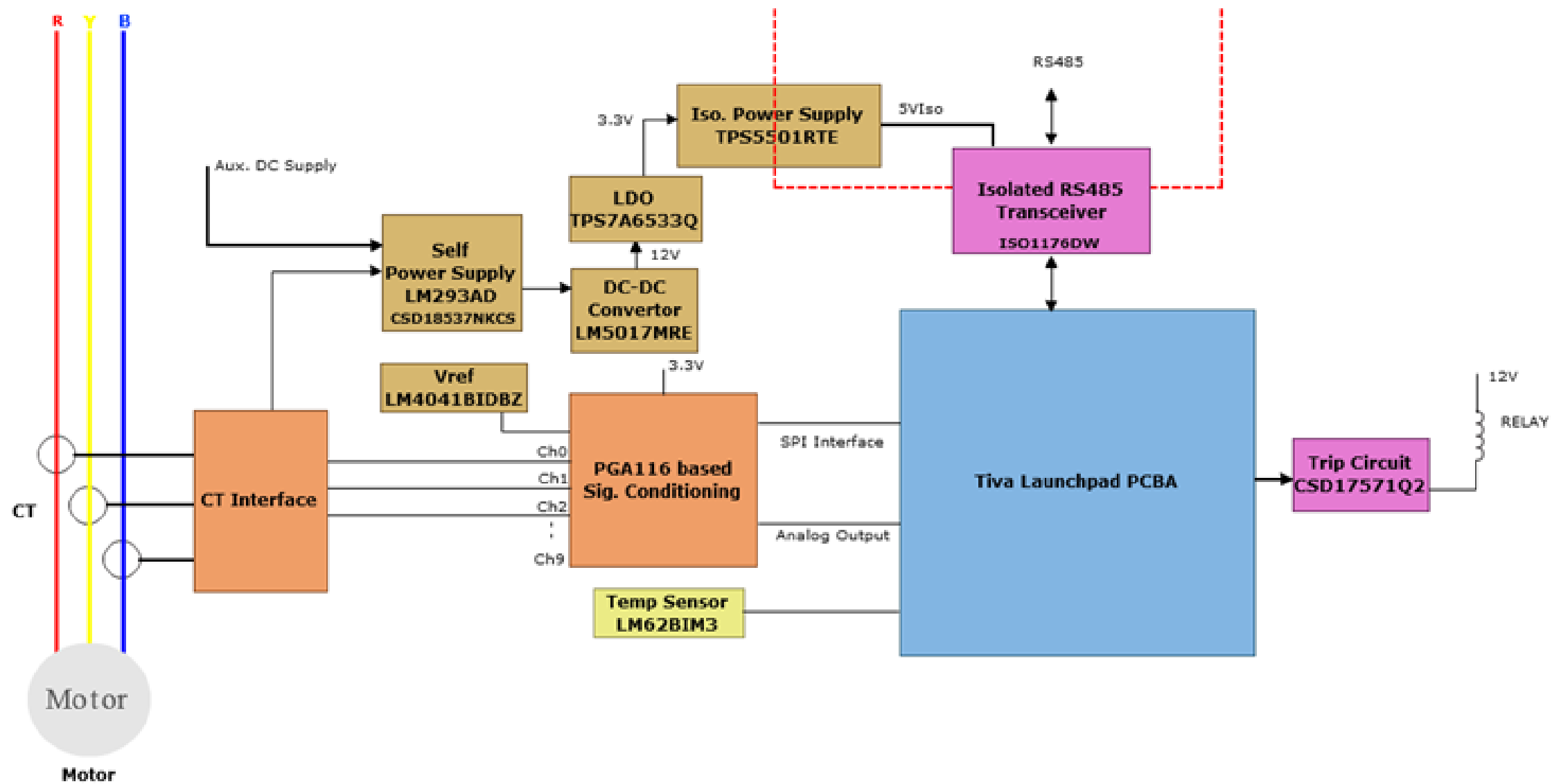
Page 7 **HARDWARE - MISCELLANEOUS**

Revision History	
Revision	Notes

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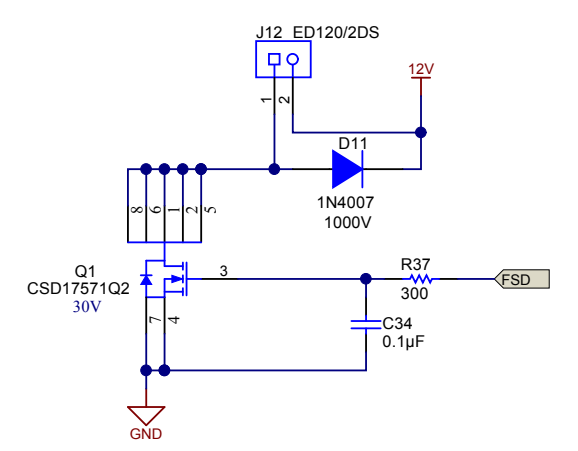
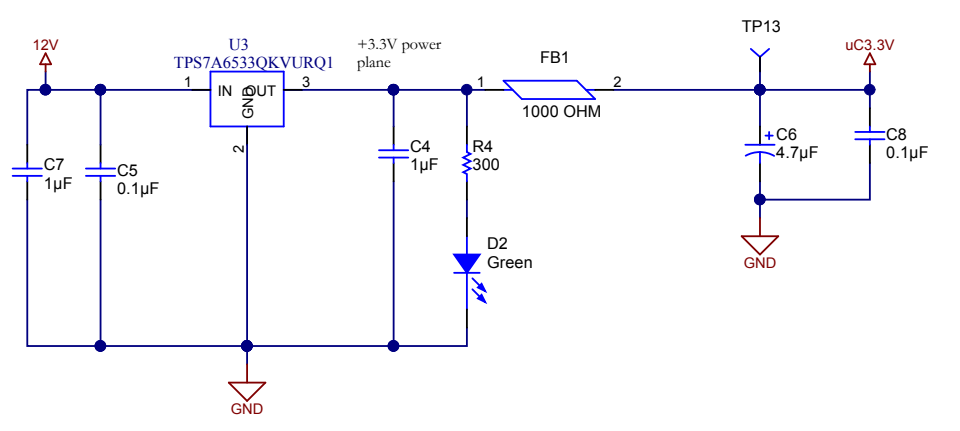
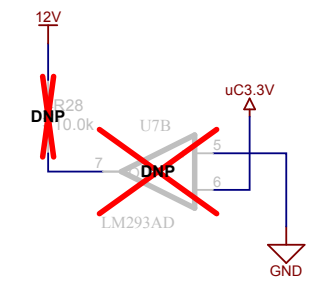
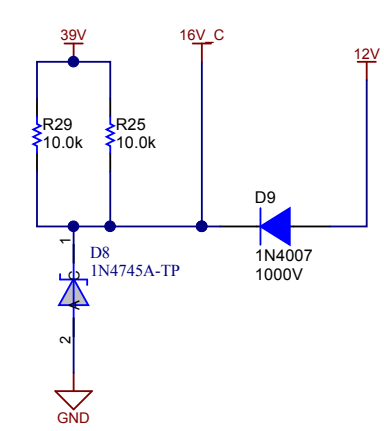
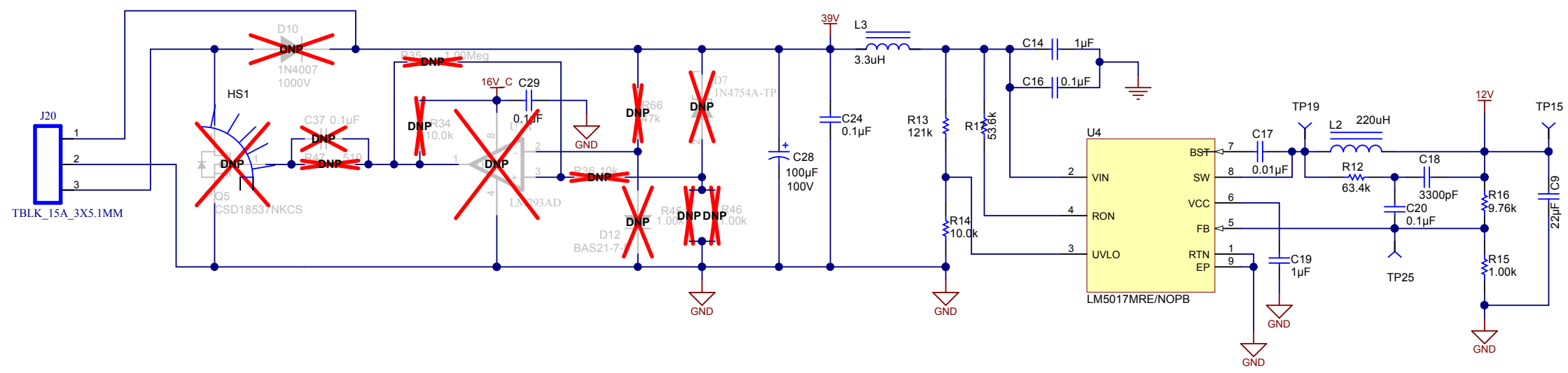
Number: TIDA-00191	Rev: E1	Designed for: Public Release	Mod. Date: 3/19/2014
SVN Rev: Not in version control	Sheet: 1 of 7	Project Title: AFE for Motor Electronic Overload Relays	
Drawn By:	File: Pg1 Index Page.SchDoc	Size: B	
Engineer: Enter name of project lead	Contact: http://www.ti.com/support		



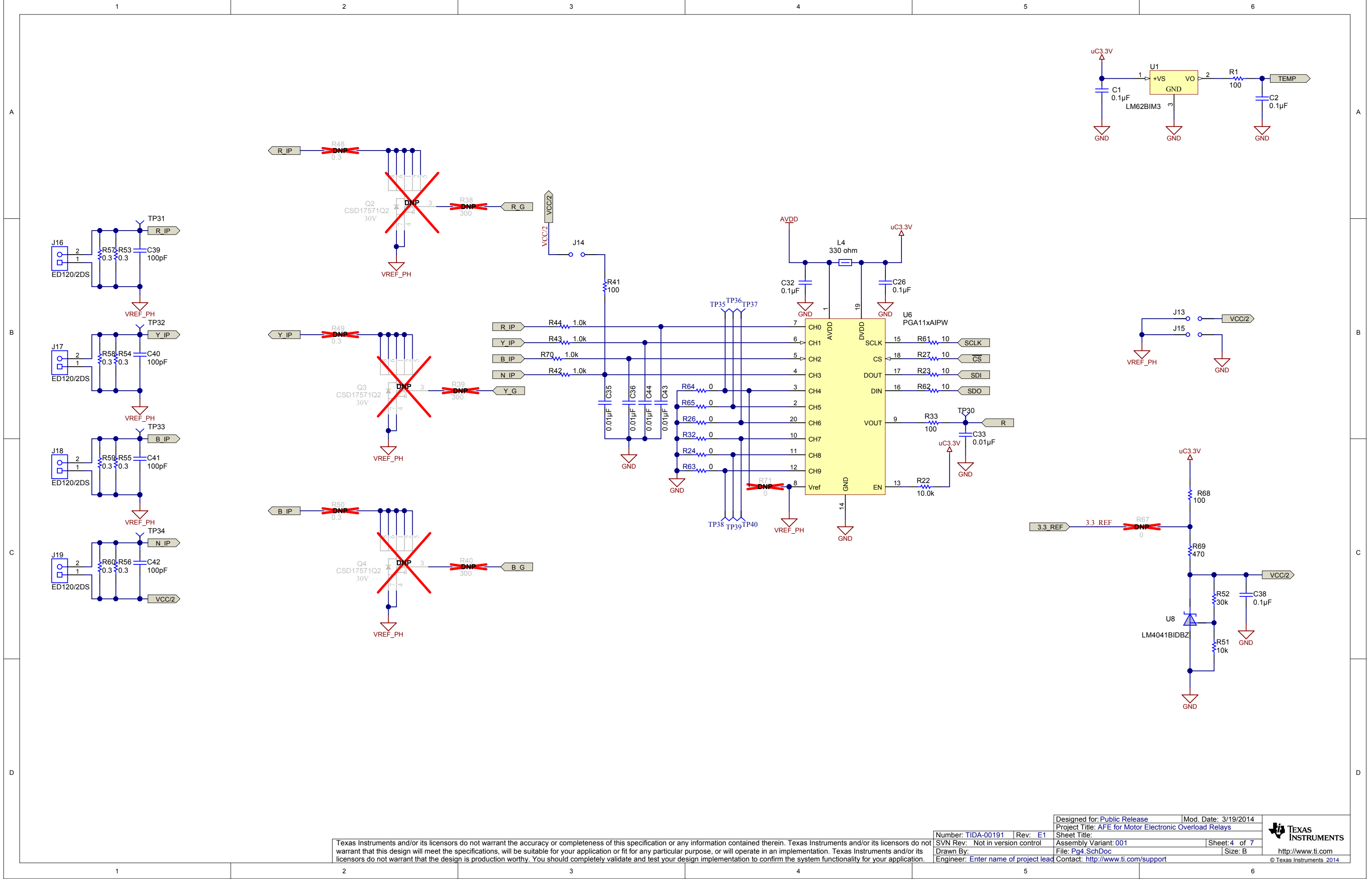


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SVN Rev: Not in version control	Assembly Variant: 001	Sheet: 2 of 7
Drawn By:	File: Pg2 Block Diagram.SchDoc	Size: B
Engineer: Enter name of project lead	Contact: http://www.ti.com/support	



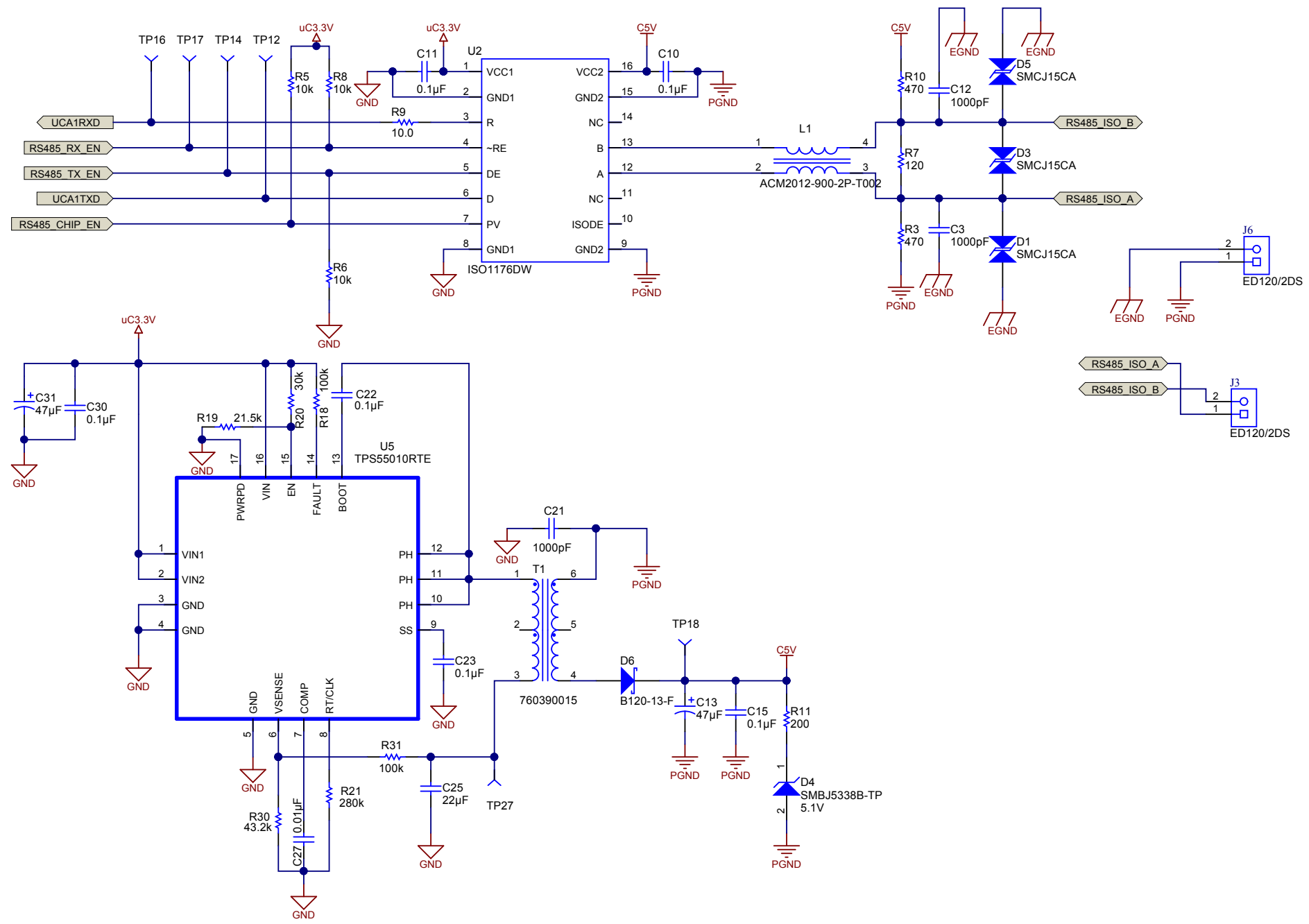
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SVN Rev: Not in version control	Assembly Variant: 001	Project Title: AFE for Motor Electronic Overload Relays	Sheet Title:
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SVN Rev: Not in version control	Sheet: 5 of 7	Project Title: AFE for Motor Electronic Overload Relays
Drawn By:	File: Pg5.SchDoc	Sheet Title:
Engineer: Enter name of project lead	Contact: http://www.ti.com/support	Assembly Variant: 001



A

A

B

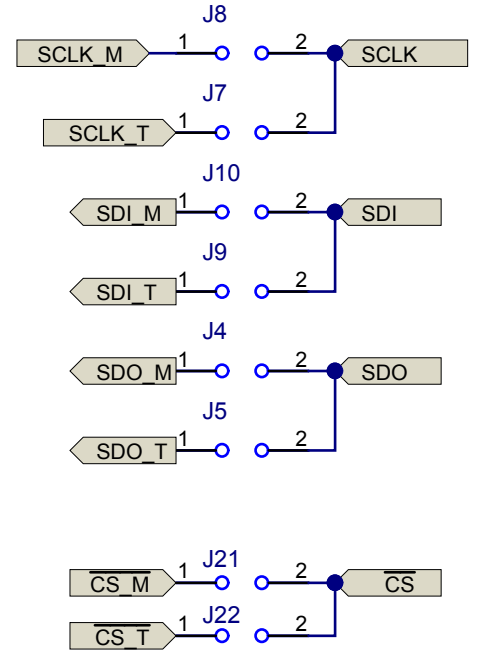
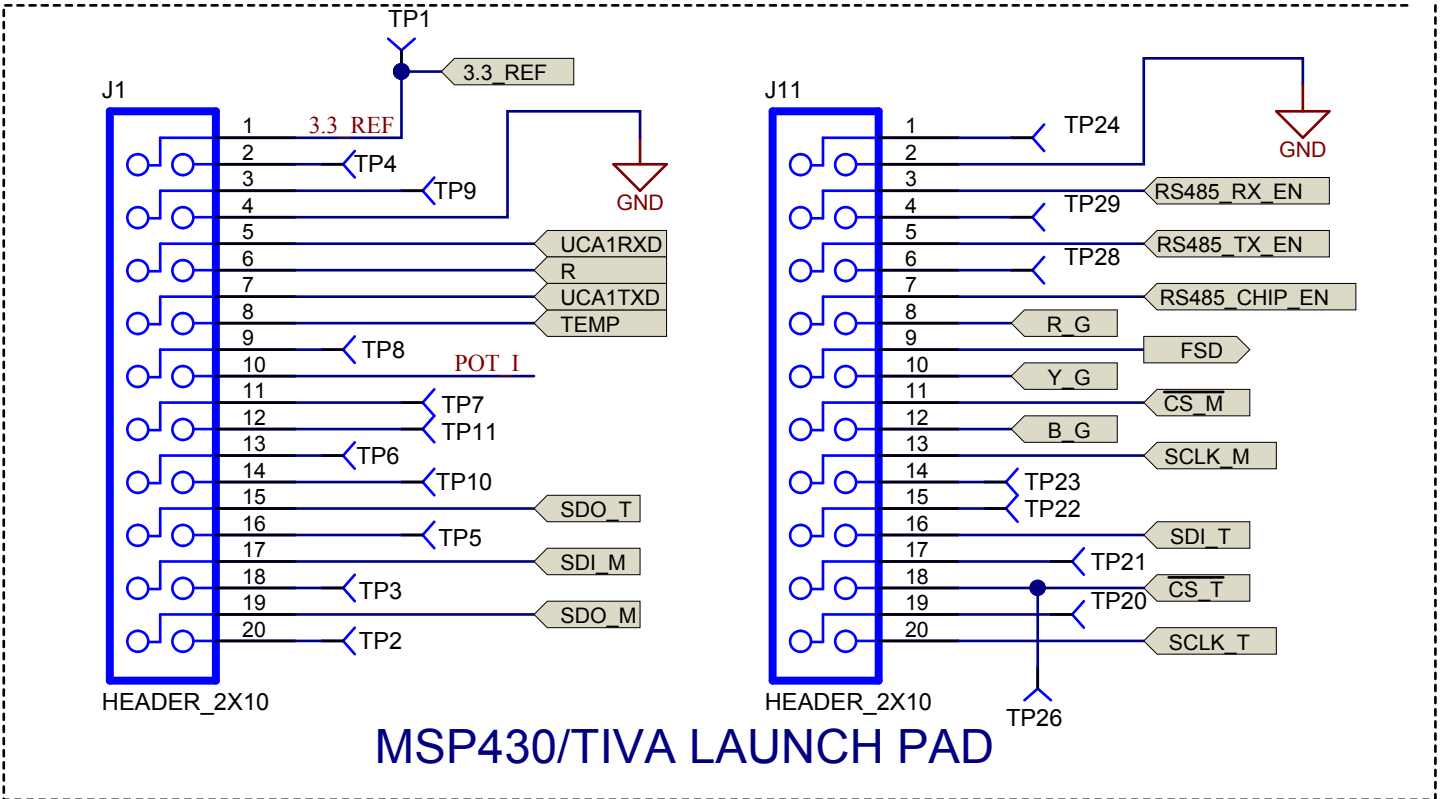
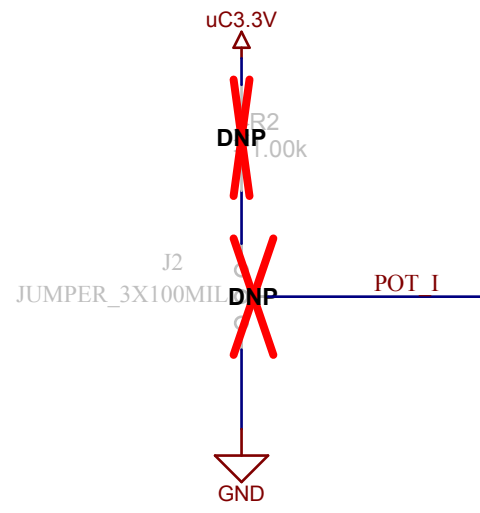
B

C

C

D

D



MSP430/TIVA LAUNCH PAD

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SVN Rev: Not in version control	Sheet Title:	Project Title: AFE for Motor Electronic Overload Relays	
Drawn By:	File: Pg6.SchDoc	Sheet: 6 of 7	Size: A4
Engineer: Enter name of project lead	Contact: http://www.ti.com/support	http://www.ti.com	

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H1 NY PMS 440 0025 PH H2 NY PMS 440 0025 PH H3 NY PMS 440 0025 PH H4 NY PMS 440 0025 PH

H6 1902C H5 1902C H9 1902C H8 1902C

H7 MH 3.2MM

FID1 FID2 FID3 FID4 FID5 FID6

PCB Number: TIDA-00191
PCB Rev: E1

PCB
LOGO
Texas Instruments

Label Table

Variant	Label Text
001	ChangeMe!
002	ChangeMe!

LBL1
PCB Label
Size: 0.65" x 0.20"

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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SVN Rev: Not in version control	Assembly Variant: 001	Project Title: AFE for Motor Electronic Overload Relays	Sheet Title:
Drawn By:	File: Pg7 Hardware.SchDoc	Sheet: 7 of 7	Size: B
Engineer: Enter name of project lead	Contact: http://www.ti.com/support	http://www.ti.com	



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